

### PNP SILICON PLANAR MEDIUM POWER HIGH GAIN TRANSISTOR

### **Features**

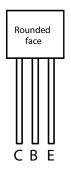
## **Mechanical Data**

- 200 Volt V<sub>CEO</sub>
- Gain of 250 at I<sub>C</sub> = 0.3 Amps
- Very low saturation voltage

Case: E-Line



E-Line TO92 Compatible



Bottom View

Pin Configuration

# **Maximum Ratings**

| Characteristic               | Symbol           | Value | Unit |
|------------------------------|------------------|-------|------|
| Collector-Base Voltage       | V <sub>CBO</sub> | -200  | V    |
| Collector-Emitter Voltage    | V <sub>CEO</sub> | -200  | V    |
| Emitter-Base Voltage         | V <sub>EBO</sub> | -5    | V    |
| Peak Pulse Current           | I <sub>CM</sub>  | -1    | A    |
| Continuous Collector Current | Ic               | -0.5  | A    |

## **Thermal Characteristics**

| Charac   | teristic                                   | Symbol                            | Value       | Unit        |  |
|--|--|-----------------------------------|-------------|-------------|--|
| Practical Power Dissipation (Note 1)                         |  | P <sub>totp</sub>                 | 1.5         | W           |  |
| Power Dissipation  | T <sub>A</sub> = 25°C<br>Derate above 25°C | P <sub>tot</sub>                  | 1<br>5.7    | W<br>mW /°C |  |
| Thermal Resistance Junction to                               | Ambient <sub>1</sub> (Note 2)              | $R_{	heta JA1}$                   | 175         | °C/W        |  |
| Thermal Resistance Junction to Ambient <sub>2</sub> (Note 2) |  | R <sub>0</sub> JA2                | 116         | °C/W        |  |
| Thermal Resistance Junction to                               | Case                                       | $R_{	heta JC}$                    | 70          | °C/W        |  |
| Operating and Storage Temper                                 | ature Range                                | T <sub>J</sub> , T <sub>STG</sub> | -55 to +200 | °C          |  |

Notes

- 1. The power which can be dissipated assuming the device is mounted in a typical manner on a P.C.B. with copper equal to 1 inch square minimum
- 2. Device mounted on P.C.B. with copper equal to 1 sq. Inch minimum.



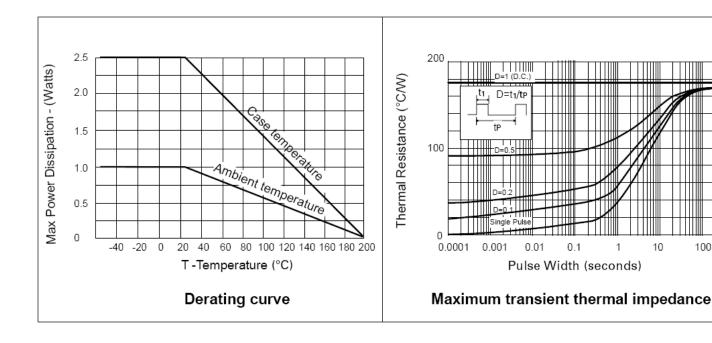


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## Electrical Characteristics @TA = 25°C unless otherwise specified

| Characteristic                                 | Symbol               | Min                      | Тур   | Max                  | Unit           | Test Condition   |
|--|----------------------|--------------------------|-------|----------------------|----------------|--|
| Collector-Base Breakdown Voltage               | $V_{(BR)CBO}$        | -200                     | -     | -                    | ٧              | $I_C = -100 \mu A$   |
| Collector-Emitter Breakdown Voltage (Note 3)   | V <sub>(BR)CEO</sub> | -200                     | -     | -                    | V              | $I_C = -10 \text{mA}$  |
| Emitter-Base Breakdown Voltage                 | V <sub>(BR)EBO</sub> | -5                       | -     | i                    | V              | $I_E = -100 \mu A$   |
| Collector Cutoff Current                       | $I_{CBO}$            | -                        | -     | -0.1                 | μΑ             | V <sub>CB</sub> = -150V  |
| Emitter Cutoff Current                         | I <sub>EBO</sub>     | -                        | -     | -0.1                 | . μA           | $V_{EB} = -4V$   |
| Collector-Emitter Saturation Voltage (Note 3)  | $V_{CE(sat)}$        | -                        | -     | -0.2<br>-0.3<br>-0.3 | mV<br>mV<br>mV | $I_C = -50$ mA, $I_B = -2$ mA<br>$I_C = -100$ mA, $I_B = -5$ mA<br>$I_C = -200$ mA, $I_B = -20$ mA   |
| Base-Emitter Saturation Voltage (Note 3)       | V <sub>BE(sat)</sub> | -                        | -     | -0.95                | mV             | $I_C = -200 \text{mA}, I_B = -20 \text{mA}$  |
| Base-Emitter Turn-On Voltage (Note 3)          | $V_{BE(on)}$         | -                        | -0.67 |                      | mV             | $I_C = -200 \text{mA}, V_{CE} = -10 \text{V}$  |
| Static Forward Current Transfer Ratio (Note 3) | h <sub>FE</sub>      | 300<br>300<br>250<br>100 | -     | 800                  |                | $\begin{split} I_{C} &= -10 \text{mA}, \ V_{CE} = -5 \text{V} \\ I_{C} &= -1 \text{A}, \ V_{CE} = -5 \text{V} \\ I_{C} &= -2 \text{A}, \ V_{CE} = -5 \text{V} \\ I_{C} &= -5 \text{A}, \ V_{CE} = -5 \text{V} \end{split}$ |
| Transition Frequency                           | f <sub>T</sub>       | 100                      | -     | ı                    | MHz            | $V_{CE} = -5V$ , $I_C = -50$ mA<br>f = 50MHz   |
| Input Capacitance                              | $C_ibo$              | -                        | 225   | i                    | рF             | $V_{EB} = -0.5V. f = 1MHz$   |
| Output Capacitance                             | $C_{obo}$            | -                        | 12    | -                    | pF             | $V_{CB} = -10V. f = 1MHz$  |
| Switching Times                                | t <sub>on</sub>      | -                        | 100   | -                    | ns             | $V_{CC} = -50V, I_{C} = -100mA$  |
|  | t <sub>off</sub>     | -                        | 3200  | -                    | ns             | $I_{B1} = -I_{B2} = -10$ mA  |

3. Measured under pulsed conditions. Pulse width = 300 µs. Duty cycle ≤ 2% Notes:

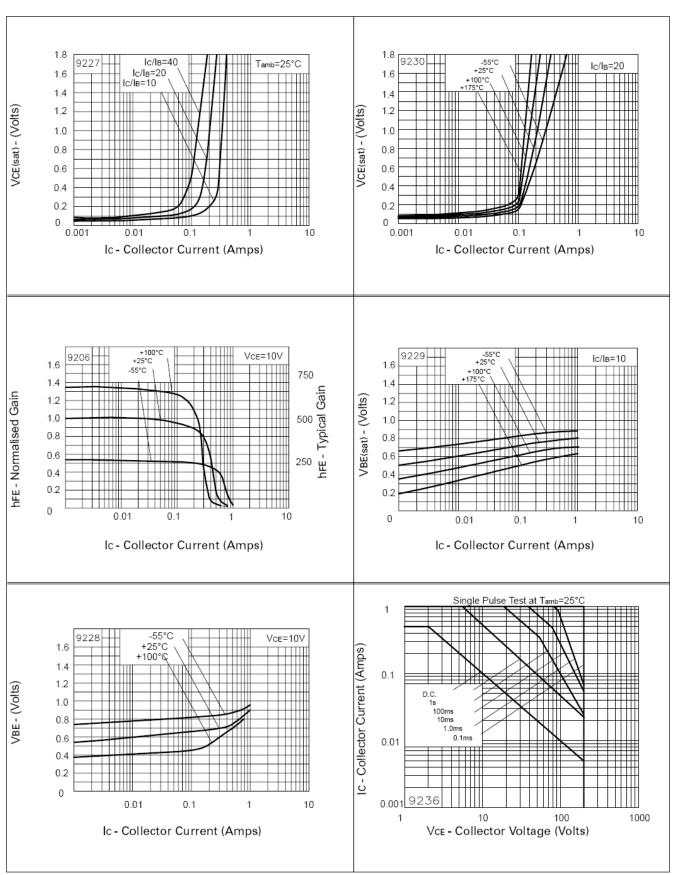


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